Display Elektronik GmbH

DATA SHEET

OLED-MODULE

DEP 128064S-Y
(C-TOUCH)

2,42" – OLED + Capacitive Touch

Product Specification   **Ver.: 9**

25.02.2021

1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	16.07.2018		First Release
1	03.12.2018		Modify Static electricity test Content of Test
2	09.02.2019		Modify Precautions in use of OLED Modules
3	18.12.2019		Modify Reliability Test and measurement conditions & Inspection specification:" Accept no dense" modify to "ignore"& Precautions
4	27.05.2020		1.Modify VDD Absolute Maximum Ratings 3.47 to 4V 2.Add 5.2 Touch Panel Controller GT911 3.Add 6.2 Touch Panel Controller GT911 4.Modify Initial code 5.Modify 6.4 TOUCH PANEL's application code
5	28.05.2020		Modify Module Classification Information
6	27.08.2020		Modify Inspection specification
7	18.11.2020		Modify Storage Precautions
8	27.01.2021		1.Modify Initial code & Brightness 2.Modify Contrast Ratio & Precautions in use of OLED Modules 3.Add Optical Characteristics Description
9	25.02.2021		Modify Precautions in use of OLED Modules

Contents

1. General Specification

The Features is described as follow:

- **n** Module Dimension: 66.80 x 41.30 x 3.71 mm

- **n** Active area: 55.01 x 27.49 mm

- **n** Dot Matrix: 128 x 64

- **n** Pixel Size: 0.4 x 0.4 mm

- **n** Pixel Pitch：0.43 x 0.43 mm

- **n** Duty: 1/64 Duty

- **n** Display Mode: Passive Matrix

- **n** Display Color: OLED , Yellow

- **n** IC: SSD1309

- **n** Interface: 8Bit-Parallel Interface (68xx/80xx) / 4-Wire SPI / I2C

- **n** Size: 2.42 Inch

- **n** CTP IC: GT911 (Goodix)

- **n** Detect Point: 1

- **n** CTP Interface: I2C

- **n** Surface: Normal Glare

2. Interface Pin Function

No.	Symbol	Function
1	NC(GND)	No connection
2	VSS	Ground.
3-10	NC	No connection
11	VDD	Power supply pin for core logic operation
12	BS1	MCU bus interface selection pins. Select appropriate logic setting as described in the following table. BS2, BS1 are pin select |	BS1	BS2
I2C	1	0
4-wire Serial	0	0
8-bit 68XX Parallel	0	1
8-bit 80XX Parallel	1	1	
13	BS2	Note (1) 0 is connected to VSS (2) 1 is connected to VDD
14	NC	No connection
15	CS#	This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW).
16	RES#	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.
17	D/C#	This pin is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data at D[7:0] will be interpreted as data. When the pin is pulled LOW, the data at D[7:0] will be transferred to a command register. In I2C mode, this pin acts as SA0 for slave address selection.
18	R/W#	This pin is read / write control input pin connecting to the MCU interface. When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.

19	E/RD#	This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.
20~27	D0~D7	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL.
28	IREF	This pin is the segment output current reference pin. IREF is supplied externally.
29	VCOMH	COM signal deselected voltage level. A capacitor should be connected between this pin and VSS.
30	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
31	NC(GND)	No connection

CTP PIN Definition

No.	Symbol	Function
1	GND	Power ground
2	VDD	Power supply
3	INT	Interrupt signal, active low, asserted to request Host start a new transaction
4	SDA	I2C data signal
5	SCL	I2C clock signal
6	RST	External reset signal, active low
7	GND	Power ground
8	GND	Power ground
9	GND	Power ground
10	GND	Power ground

3. Counter Drawing & Block Diagram
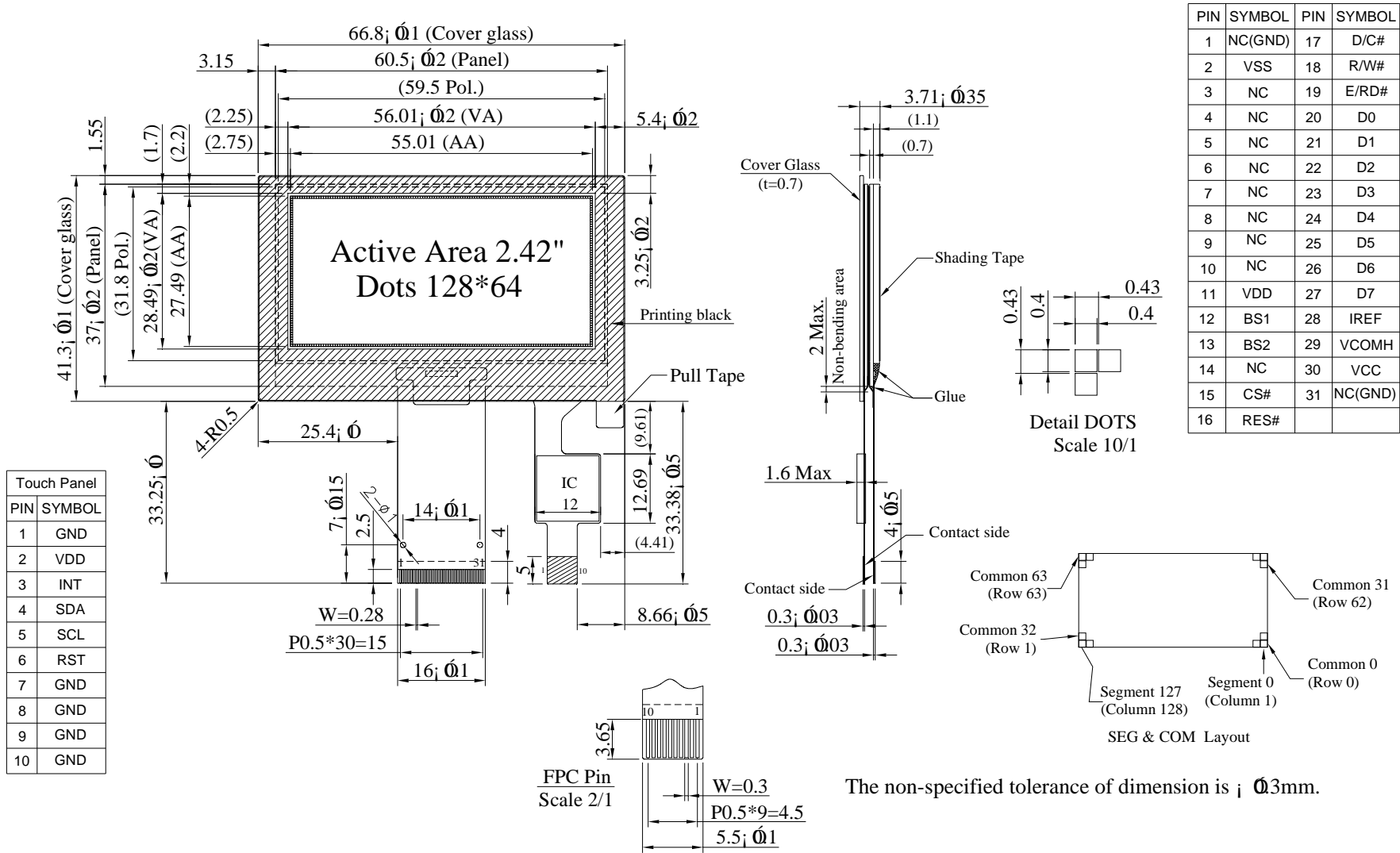
PIN	SYMBOL	PIN	SYMBOL
1	NC(GND)	17	D/C#
2	VSS	18	R/W#
3	NC	19	E/RD#
4	NC	20	D0
5	NC	21	D1
6	NC	22	D2
7	NC	23	D3
8	NC	24	D4
9	NC	25	D5
10	NC	26	D6
11	VDD	27	D7
12	BS1	28	IREF
13	BS2	29	VCOMH
14	NC	30	VCC
15	CS#	31	NC(GND)
16	RES#		

Touch Panel

PIN	SYMBOL
1	GND
2	VDD
3	INT
4	SDA
5	SCL
6	RST
7	GND
8	GND
9	GND
10	GND

66.8¡ 1 (Cover glass)
60.5¡ 2 (Panel)
(59.5 Pol.)
56.01¡ 2 (VA)
55.01 (AA)
3.15
(2.25)
(2.75)
5.4¡ 2
3.25¡ 2
1.55
(1.7)
(2.2)

41.3¡ 1 (Cover glass)
37¡ 2 (Panel)
(31.8 Pol.)
28.49¡ 2(VA)
27.49 (AA)

Active Area 2.42"
Dots 128*64

Printing black

33.25¡
4-R0.5
25.4¡
7¡ 15
2.5
14¡ 1
4
IC 12
(9.61)
12.69
33.38¡ 5
(4.41)
5
W=0.28
P0.5*30=15
16¡ 1
8.66¡ 5

Pull Tape

3.71¡ 35
(1.1)
(0.7)
Cover Glass (t=0.7)
Shading Tape
2 Max.
Non-bending area
Glue
1.6 Max
4¡ 5
Contact side
Contact side
0.3¡ 03
0.3¡ 03

Detail DOTS
Scale 10/1
0.43
0.4
0.43
0.4

Common 63 (Row 63)
Common 32 (Row 1)
Common 31 (Row 62)
Common 0 (Row 0)
Segment 127 (Column 128)
Segment 0 (Column 1)
SEG & COM Layout

The non-specified tolerance of dimension is ¡ 0.3mm.

FPC Pin
Scale 2/1
3.65
W=0.3
P0.5*9=4.5
5.5¡ 1

3.1 Application Recommendations
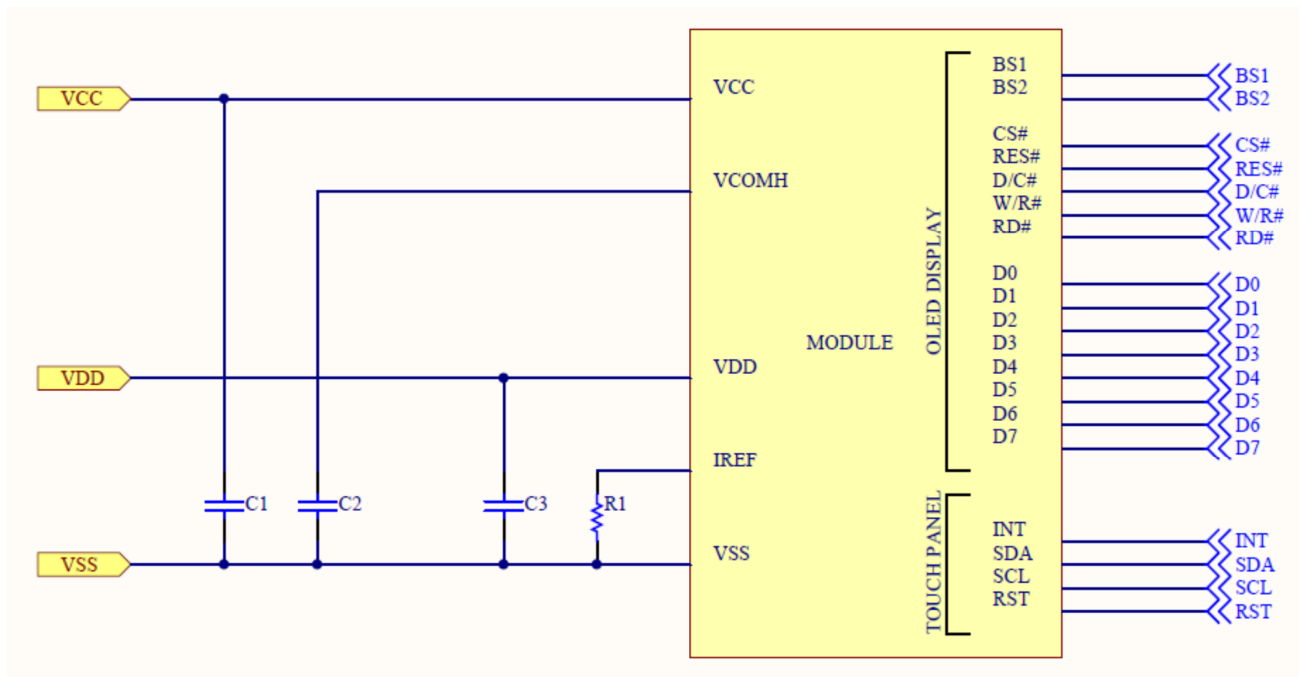
Recommended Components:

C1, C2 : 2.2uF

C3 : 1.0uF

OLED Bus Interface selection: (Must be set the BS[2:1], refer to item 3)
8-Bits 6800 and 8080 Parallel, 4 Wire SPI, I2C

TOUCH PANEL'S INTERFACE: ONLY I2C INTERFACE.

Voltage at IREF ≈ VCC – 3V. For VCC = 13V, IREF = 10uA:
R1 = (Voltage at IREF - VSS) / IREF
≈ (13 - 3)V / 10uA = 1MΩ

4. Absolute Maximum Ratings

4.1 Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-20	+70	°C	-
Storage Temperature	TSTG	-30	+80	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".
Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 ''Electrical Characteristics''. If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate

4.2 Touch Panel Controller GT911

Parameter	Symbol	Min	Max	Unit	Notes
Power Supply Voltage	VDD	2.66	3.47	V	1

Note 1: If used beyond the absolute maximum ratings, CTP IC may be permanently damaged. It is strongly recommended that the device be used within the electrical characteristics in normal operations. If exposed to the condition not within the electrical characteristics, it may affect the reliability of the device.

5. Electrical Characteristics

5.1 DC Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage for Logic	VDD	-	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	-	12.5	13.0	13.5	V
High Level Input	VIH	-	0.8×VDD	-	-	V
Low Level Input	VIL	-	-	-	0.2×VDD	V
High Level Output	VOH	-	0.9×VDD	-	-	V
Low Level Output	VOL	-	-	-	0.1×VDD	V
50% Check Board operating Current		VCC =13.0V	-	22	33	mA

5.2 Touch Panel Controller GT911

Item	Symbol	Min	Typ	Max	Unit
Supply Voltage	VDD	2.8	3.0	3.3	V
Input High Volt.	VIH	0.75xVDD		VDD+0.3	V
Input Low Volt.	VIL	-0.3	-	0.25xVDD	V
Output High Volt.	VOH	0.85xVDD	-	-	V
Output Low Volt.	VOL	-	-	0.15xVDD	V

5.3 OLED Display Initial Code Proposal

void Initial_SSD1309(){

```
        Write_command(0xAE);          // Display Off

        Write_command(0xA8);          // Select Multiplex Ratio
        Write_command(0x3F);          // Default => 0x3F (1/64 Duty)        0x1F(1/32 Duty)

        Write_command(0xD3);          //Setting Display Offset
        Write_command(0x00);          //00H Reset

        Write_command(0x20);          //Set Memory Addressing Mode
        Write_command(0x02);          //Page Addressing Mode

        Write_command(0x00);          //Set Column Address LSB

        Write_command(0x10);          //Set Column Address MSB

        Write_command(0x40);          //Set Display Start Line

        Write_command(0xA6);          //Set Normal Display

        Write_command(0xDB);          //Set Deselect Vcomh level
        Write_command(0x3C);          //~0.83xVCC

        Write_command(0xA4);          //Entire Display ON

        Write_command(0x81);          //Set Contrast Control
        Write_command(0x4F);

        Write_command(0xD5);          //SET DISPLAY CLOCK
        Write_command(0xC0);          //105HZ

        Write_command(0xA1);          //Set Segment Re-Map Default => 0xA0
                                      //0xA1 (0x01) => Column Address 0 Mapped to SEG131

        Write_command(0xC8);          //Set COM Output Scan Direction Default => 0xC0
                                       //0xC8 (0x08) => Scan from COM63 to 0

        Write_command(0xDA);          //Set COM Hardware Configuration
        Write_command(0x12);          //Alternative COM Pin

        Write_command(0xD9);          //Set Pre-Charge period
        Write_command(0x22);

        Write_command(0xAF);          // Display ON
}
```
Note: Initial code is for reference only. Please make the best adjustment with the OLED module.

5.4 TOUCH PANEL's Application Code Proposal

5.4.1 I2C address format

GT911 supports two I2C slave addresses: 0xBA/0xBB and 0x28/0x29.

Item	Write Address_W	Read Address_R
0xBA/0xBB address	0xBA	0xBB
0x28/0x29 address	0x28	0x29

5.4.2 Power on for I2C address select

The host can select the address by changing the status of Reset and INT pins during the power-on initialization phase. See the diagram below for configuration methods and timings:
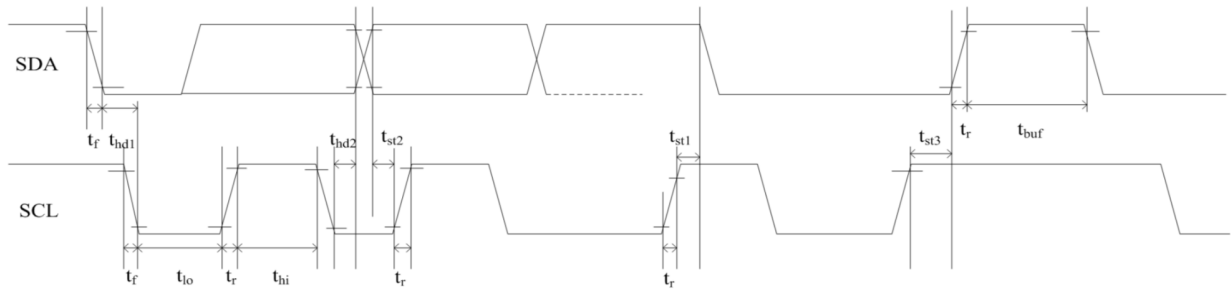
Timing for initial setting slave address to 0xBA/0xBB:
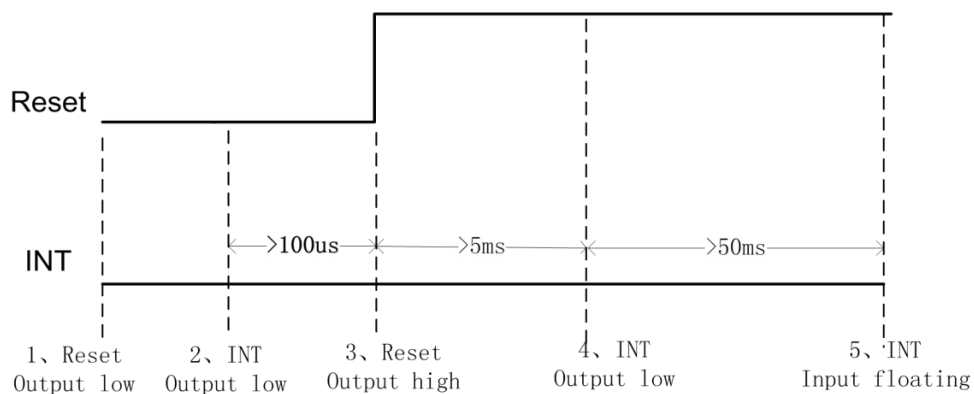
Timing for initial setting slave address to 0x28/0x29:
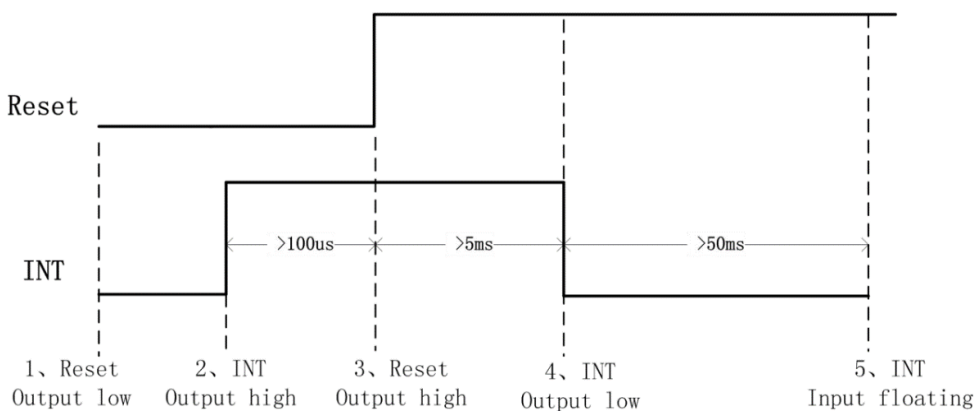
5.4.3 I2C Timing

3.3V communication interface, 400Kbps, pull up resistor is 2K ohm

Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

5.4.4 Data Transmission
(ex: slave address is 0xBA/0xBB)

Communication is always initiated by master, A high-to-low transition of SDA with SCL high is a All addressing signal are serially transmitted to and from on bus in 8-bit word. GT911 sends a "0" to acknowledge when the addressing word is 0xBA/BB (or 0x28/0x29).

This happens during the ninth clock cycle. If the slave address is not matched, GT911 will stay in idle state.
The data words are serially transmitted to and from in 9-bit formation: 8-bit data + 1-bit ACK or NACK sent by GT911. Data changes during SCL low periods & keeps valid during SCL high.

A low-to-high transition of SDA with SCL high is a stop condition.

5.4.5 Write Data to GT911
(ex: slave address is 0xBA/0xBB)

S	Address_W	ACK	Register_H	ACK	Register_L	ACK	Data_1	ACK	⋯⋯	Data_n	ACK	E
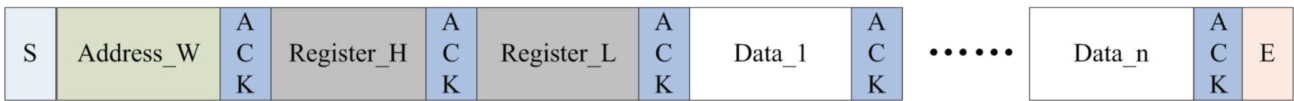
Write operations

Please check the above figure, master start the communication first, and then sends device address 0XBA preparing for a write operation.

After receiving ACK from GT911, master sends out 16-bit register address, and then the data word in 8-bit, which is going to be wrote into GT911.

The address pointer of GT911 will automatically increase one after one byte writing, so master can sequentially write in one operation. When operation finished, master stop the communication.

5.4.6 Read Data from GT911
(ex: slave address is 0xBA/0xBB)

S	Address_W	ACK	Register_H	ACK	Register_L	ACK	E	S	Address_R	ACK	Data_1	ACK	⋯⋯	Data_n	NACK	E

Set address pointer — Read data
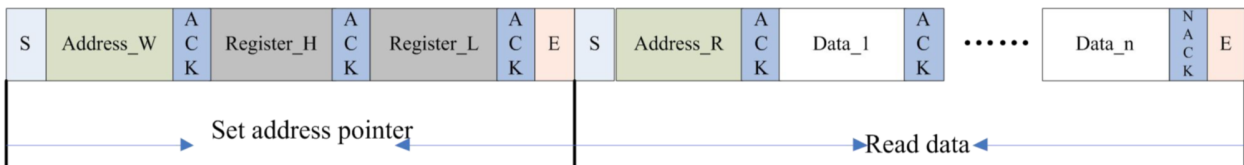
Read operations

The diagram above is the timing sequence of the host reading data from GT911. First, the host issues a Start condition and sends 0XBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where reading starts) to the slave device. Then the host sets register addresses which need to be read.

Also after receiving ACK, the host issues the Start condition once again and sends 0XBB (Read Operation). After receiving ACK, the host starts to read data.

GT911 also supports continuous Read Operation and, by default, reads data continuously. Whenever receiving a byte of data, the host sends an ACK signal indicating successful reception. After receiving the last byte of data, the host sends a NACK signal followed by a STOP condition which terminates communication.

5.4.7 Coordinates Information

Addr	Access	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
0x814E	R/W	buffer status	large detect	Reserved		number of touch points			
0x814F	R	track id							
0x8150	R	point 1 x coordinate (low byte)							
0x8151	R	point 1 x coordinate (high byte)							
0x8152	R	point 1 y coordinate (low byte)							
0x8153	R	point 1 y coordinate (high byte)							
0x8154	R	Point 1 size (low byte)							
0x8155	R	point 1 size (high byte)							
0x8156	R	Reserved							

* Addr = [Register_H : Register_L]

Buffer status, 1 = coordinate (or key) is ready for host to read; 0 = coordinate (or key) is not ready and data is not valid. After reading coordinates, host should configure this flag (or the entire byte) to 0 via I2C.

Large detect, 1 indicates there is large-area touch on TP.

6. Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V)θ	-	160	-	-	deg
	(H)φ	-	160	-	-	deg
Contrast Ratio	CR	Dark	10000:1	-	-	-
Response Time	T rise	-	-	10	-	μs
	T fall	-	-	10	-	μs
Display with 50% check Board Brightness (Note1)			100	150	-	cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	-
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	-

Note 1: The brightness value is based on the setting of Vcc equal to the Typical value.
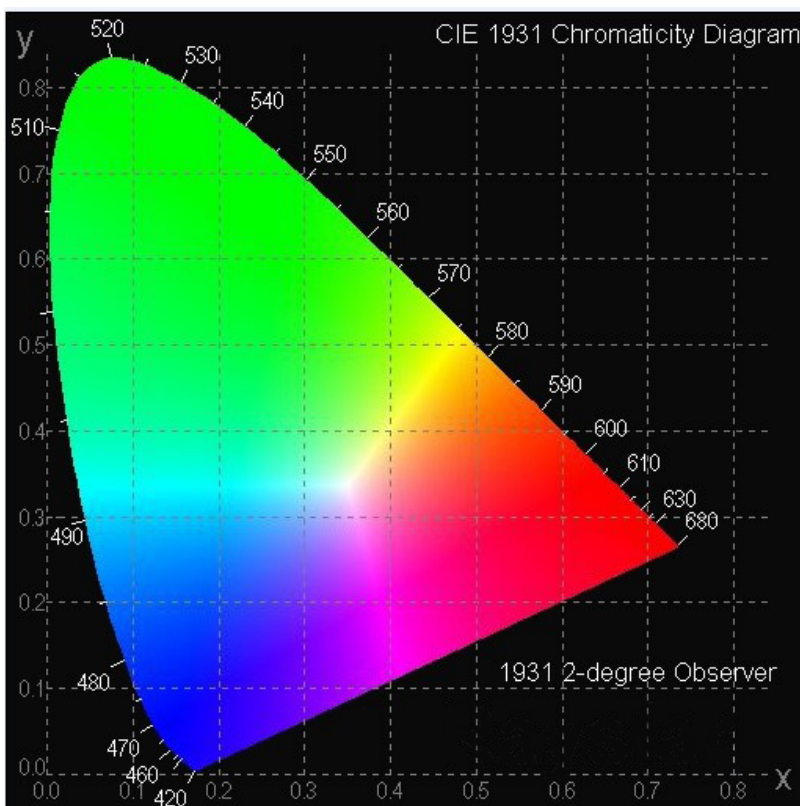
7. OLED Lifetime
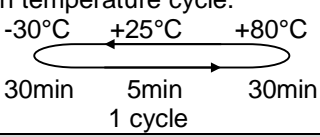
ITEM	Conditions	Min	Typ	Remark
Operating Lifetime	Ta=25°C / Initial 50% check board brightness 100cd/m²	50.000 Hrs	-	Note

Notes:
1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
3. Screen saving mode will extend OLED lifetime.

8. Reliability

Content of Reliability Test

Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Applicable Standard**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	+80°C 240hrs	____
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 240hrs	____
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	+70°C 240hrs	____
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 240hrs	____
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	+60°C,90%RH 240hrs	____
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	+60°C,90%RH 120hrs	____
Temperature Cycle	Endurance test applying the low and high temperature cycle. -30°C +25°C +80°C 30min 5min 30min 1 cycle	-30°C /+80°C 30 cycles	____
Mechanical Test			
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	____
Others			
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge Model ±4kV,10 times	____

*** Supply voltage for OLED system =Operating voltage at 25°C

Test and measurement conditions

1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23°C ± 5°C; 55% ± 15% RH.
2. All-pixels on/off exchange is used as operation test pattern.
3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

1. The function test is OK.
2. No observable defects.
3. Luminance: > 50% of initial value.
4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

9. Inspection specification

Inspection Standard:

MIL-STD-105E table normal inspection single sample level II.

Definition

1 Major defect: The defect that greatly affect the usability of product.

2 Minor defect: The other defects, such as cosmetic defects, etc.

Definition of inspection zone:

```
            C
            B
            A
```
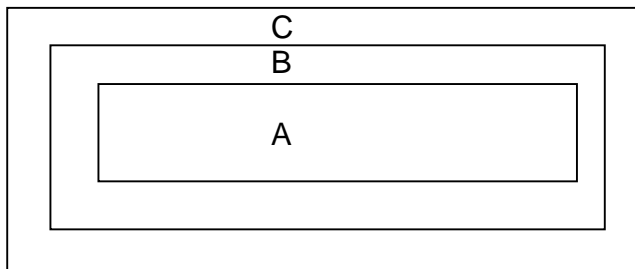
Zone A: Active Area

Zone B: Viewing Area except Zone A
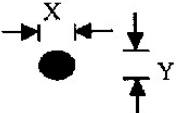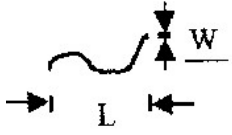
Zone C: Outside Viewing Area
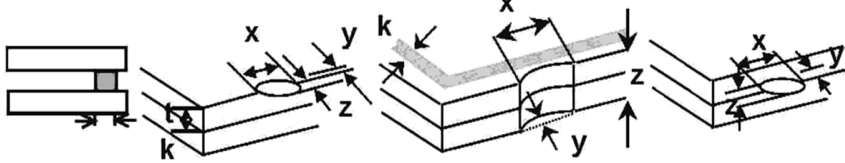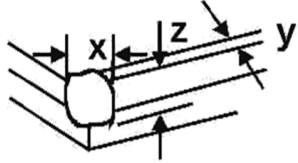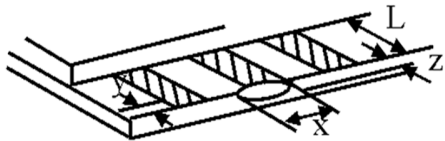
Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer`s product.

Inspection Methods

1 The general inspection: Under fluorescent light illumination: 750~1500 Lux, about 30cm viewing distance, within 45º viewing angle, under 25°C ± 5°C.

2 The luminance and color coordinate inspection: By SR-3 or BM-7 or the equal equipments in the dark room, under 25°C ± 5°C.
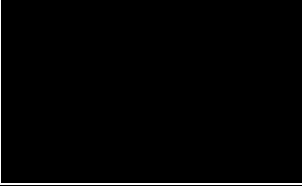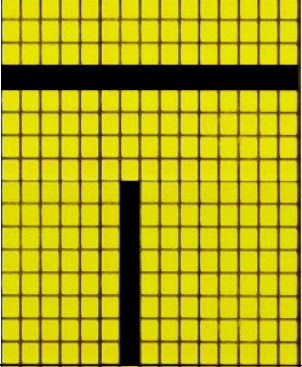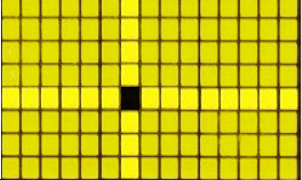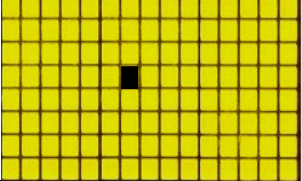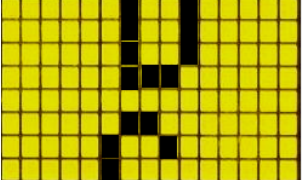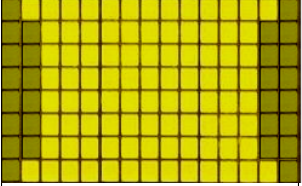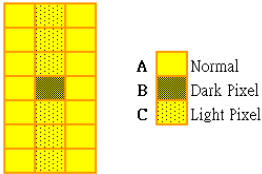
NO	Item	Criterion	AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65
02	Black or white spots on OLED (display only)	2.1 White and black spots on display □0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm.	2.5

NO	Item	Criterion	AQL
03	OLED black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi=(x + y) / 2$ <table><tr><td>SIZE</td><td>Acceptable QTY</td><td>Zone</td></tr><tr><td>Φ≦0.10</td><td>ignore</td><td>A+ B,</td></tr><tr><td>0.10 < Φ≦0.20</td><td>2</td><td>A+ B</td></tr><tr><td>0.20 < Φ≦0.25</td><td>1</td><td>A+ B</td></tr><tr><td>0.25 < Φ</td><td>0</td><td>A+ B</td></tr></table>	2.5
		3.2 Line type : (As following drawing) <table><tr><td>Length</td><td>Width</td><td>Acceptable Q TY</td><td>Zone</td></tr><tr><td>---</td><td>W≦0.02</td><td>ignore</td><td>A+B</td></tr><tr><td>L≦3.0</td><td>0.02 < W≦0.03</td><td rowspan="2">2</td><td>A+B</td></tr><tr><td>L≦2.5</td><td>0.03 < W≦0.05</td><td>A+B</td></tr><tr><td>---</td><td>0.05 < W</td><td>As round type</td><td></td></tr></table>	2.5
04	Polarizer bubbles	4.1 If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table><tr><td>Size Φ</td><td>Acceptable Q TY</td><td>Zone</td></tr><tr><td>Φ≦0.20</td><td>ignore</td><td>A+B</td></tr><tr><td>0.20 < Φ≦0.50</td><td>3</td><td>A+B</td></tr><tr><td>0.50 < Φ≦1.00</td><td>2</td><td>A+B</td></tr><tr><td>1.00 < Φ</td><td>0</td><td>A+B</td></tr><tr><td>Total Q TY</td><td>3</td><td></td></tr></table> 4.2 The polarizer dent follows this specification.	2.5
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination.	

NO	Item	Criterion	AQL
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: | z: Chip thickness	y: Chip width	x: Chip length
---	---	---
Z≦1/2t	Not over viewing area	x≦1/8a
1/2t < z≦2t	Not exceed 1/3k	x≦1/8a | ⊙If there are 2 or more chips, x is total length of each chip.	2.5
		6.1.2 Corner crack: | z: Chip thickness	y: Chip width	x: Chip length
---	---	---
Z≦1/2t	Not over viewing area	x≦1/8a
1/2t < z≦2t	Not exceed 1/3k	x≦1/8a | ⊙If there are 2 or more chips, x is the total length of each chip.	2.5
	Glass crack	Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad : | y: Chip width	x: Chip length	z: Chip thickness
---	---	---
y≦0.5mm	x≦1/8a	0 < z ≦ t		2.5

NO	Item	Criterion	AQL
06	Glass crack	6.2.2 Non-conductive portion: | y: Chip width	x: Chip length	z: Chip thickness | |---|---|---| | $y \leqq L$ | $x \leqq 1/8a$ | $0 < z \leqq t$ | ◉If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ◉If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. | y: width | x: length | |---|---| | $y \leqq 1/3L$ | $x \leqq a$ |	2.5
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65

NO	Item	Criterion	AQL
10	PCB , COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel

10. Precautions in use of OLED Modules

(1) Avoid applying excessive shocks to module or making any alterations or modifications to it.

(2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.

(3) Don't disassemble the OLED display module.

(4) Do not apply input signals while the logic power is off.

(5 Don't operate it above the absolute maximum rating.

(6) Don't drop, bend or twist OLED display module.

(7) Soldering: only to the I/O terminals.

(8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.

(9) DISPLAY has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

(10) DISPLAY has the right to upgrade or modify the product function.

(11) For COG & COF structure OLED products, customers should reserve VCC (VPP) adjustment function or software update function when designing OLED supporting circuit. (The progress of OLED light-emitting materials will increase the conversion efficiency and the brightness. The brightness can be adjusted if necessary)..


10.1 Handling Precautions

(1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.

(2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.

(3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So be careful not to apply pressure to these sections.

(4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.

(5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.

  * Scotch Mending Tape No. 810 or an equivalent

   Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

   Also, pay attention that the following liquid and solvent may spoil the polarizer:

  * Water

  * Ketone

  * Aromatic Solvents

(6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.

7) Do not touch the following sections whenever possible while handling the OLED display modules.

* Pins and electrodes
* Pattern layouts such as the TCP & FPC
(8) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.
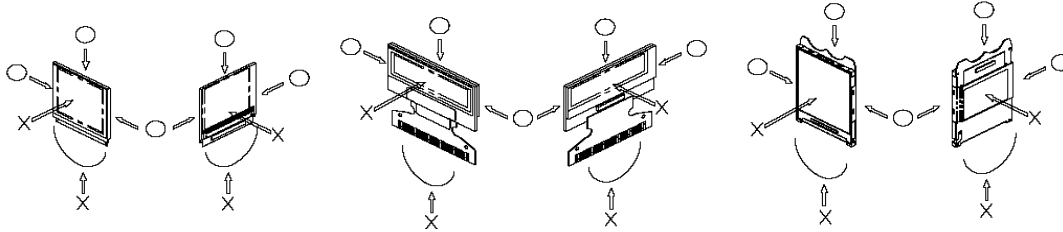
(7) Do not apply stress to the LSI chips and the surrounding molded sections.
(8) Do not disassemble nor modify the OLED display module.
(9) Do not apply input signals while the logic power is off.
(10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
   * Be sure to make human body grounding when handling OLED display modules.
   * Be sure to ground tools to use or assembly such as soldering irons.
   * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
   * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
(11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
(12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

10.2 Storage Precautions
(1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. And, also, place in the temperature 25±5°C and Humidity below 65% RH. (We recommend you to store these modules in the packaged state when they were shipped from DISPLAY. At that time, be careful not to let water drops adhere to the packages or bags.)
(2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

10.3 Designing Precautions
(1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
(2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
(3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD/VCC). (Recommend value: 0.5A)

(4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.

(5) As for EMI, take necessary measures on the equipment side basically.

(6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.

(7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.

(8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.

(9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.

(10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.

11) The limitation of FPC and Film bending.
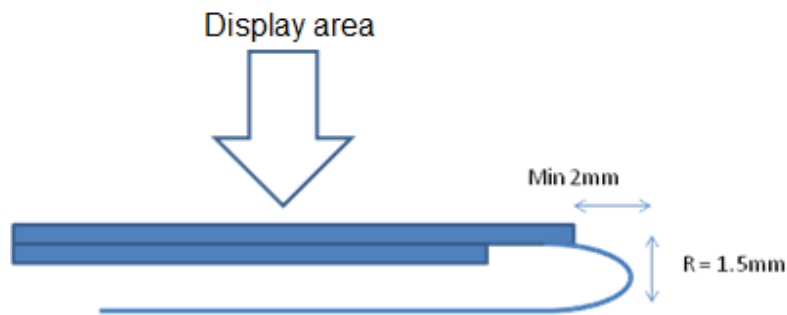
(12) The module should be fixed balanced into the housing, or the module may be twisted.
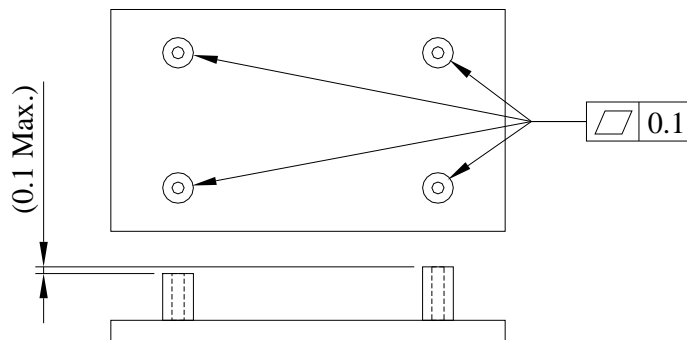
(13) Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

10.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.